

Electronic Patent Application Fee Transmittal

Application Number:	09712749			
Filing Date:	14-Nov-2000			
Title of Invention:	Low profile integrated module interconnects and method of fabrication			
First Named Inventor/Applicant Name:	Chia-Yu Fu			
Filer:	David George Dolezal/Stacie Herrera			
Attorney Docket Number:	CT00-020			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Petition-revive unintent. abandoned appl	1453	1	1540	1540
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1540